

## TO-252 Pin Configuration

BVDSS	R <sub>DS(ON)</sub>	I <sub>D</sub>
30V	4.1mΩ	74A

### Features

- 30V, 74A,  $R_{DS(ON)} = 4.1m\Omega @ V_{GS} = 10V$
- Improved  $dv/dt$  capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Networking
- Load Switch
- LED applications



## MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current – Continuous (TC=25°C)	I <sub>D</sub>	74	A
Drain Current – Continuous (TC=100°C)		46.8	A
Drain Current – Pulsed <sup>1</sup>	I <sub>DM</sub>	296	A
Single Pulse Avalanche Energy <sup>2</sup>	E <sub>AS</sub>	115	mJ
Single Pulse Avalanche Current <sup>2</sup>	I <sub>AS</sub>	48	A
Power Dissipation (TC=25°C)	P <sub>D</sub>	54.3	W
Power Dissipation – Derate above 25°C		0.44	W/°C
Storage Temperature Range	T <sub>STG</sub>	-50 to +150	°C
Operating Junction Temperature Range	T <sub>J</sub>	-50 to +150	°C

### Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to ambient	R <sub>θJA</sub>	---	62	°C/W
Thermal Resistance Junction to Case	R <sub>θJC</sub>	---	2.3	°C/W

## MOSFET ELECTRICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ unless otherwise specified

### Off Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.03	---	$V/^\circ\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=24V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA

### On Characteristics

Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=15A$	---	3.4	4.1	m $\Omega$
		$V_{GS}=4.5V, I_D=10A$	---	4.7	6	m $\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	1.6	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	-4.17	---	$\text{mV}/^\circ\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=3A$	---	10	---	S

### Dynamic and switching Characteristics

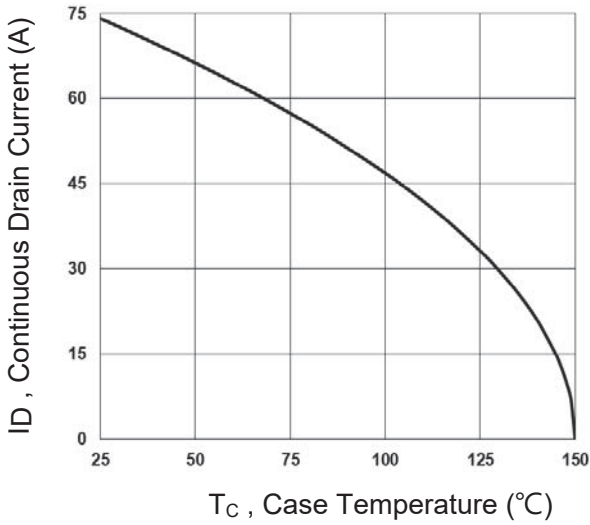
Total Gate Charge <sup>3, 4</sup>	$Q_g$	$V_{DS}=15V, V_{GS}=10V, I_D=15A$	---	34.6	70	nC
Gate-Source Charge <sup>3, 4</sup>	$Q_{gs}$		---	5.5	11	
Gate-Drain Charge <sup>3, 4</sup>	$Q_{gd}$		---	6.8	13	
Turn-On Delay Time <sup>3, 4</sup>	$T_{d(on)}$	$V_{DD}=15V, V_{GS}=10V, R_G=3.3\Omega$ $I_D=1A$	---	9.7	20	ns
Rise Time <sup>3, 4</sup>	$T_r$		---	15.8	31	
Turn-Off Delay Time <sup>3, 4</sup>	$T_{d(off)}$		---	37.4	75	
Fall Time <sup>3, 4</sup>	$T_f$		---	12	24	
Input Capacitance	$C_{iss}$	$V_{DS}=15V, V_{GS}=0V, F=1\text{MHz}$	---	1910	3800	pF
Output Capacitance	$C_{oss}$		---	300	600	
Reverse Transfer Capacitance	$C_{rss}$		---	230	460	
Gate resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	---	1.14	---	$\Omega$

### Drain-Source Diode Characteristics and Maximum Ratings

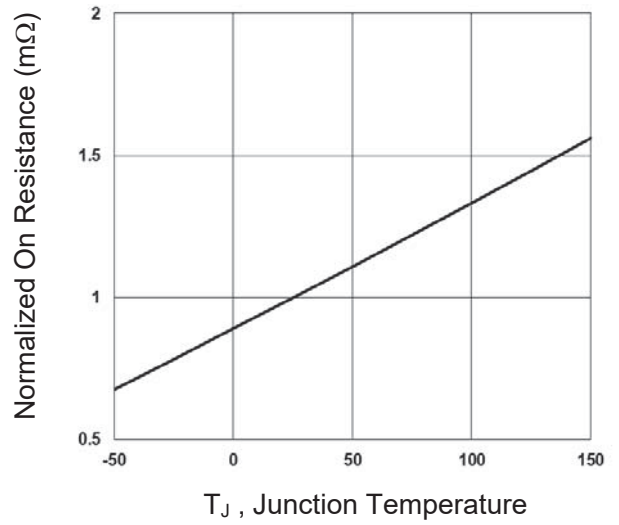
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	$I_S$	$V_G=V_D=0V$ , Force Current	---	---	74	A
Pulsed Source Current	$I_{SM}$		---	---	148	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V
Reverse Recovery Time	$t_{rr}$	$V_{DS}=30V, I_S=10A, di/dt=100A/\mu s$	---	2.33	---	$\mu s$
Reverse Recovery Charge	$Q_{rr}$	$T_J=25^\circ\text{C}$	---	48.9	---	$\mu C$

Note :

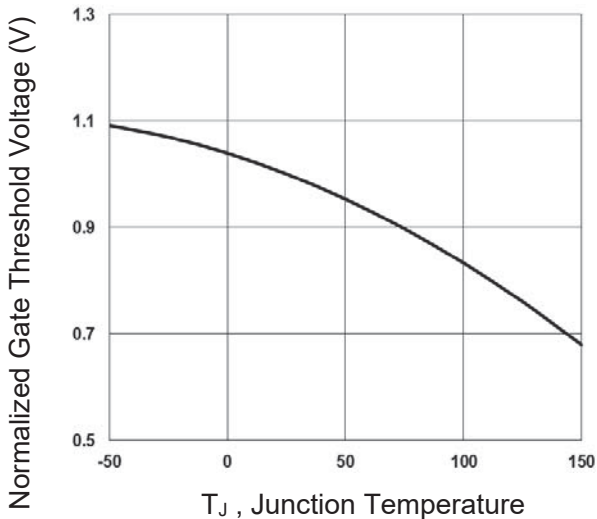
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=48A., R_G=25\Omega, \text{Starting } T_J=25^\circ\text{C}$ .
3. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.



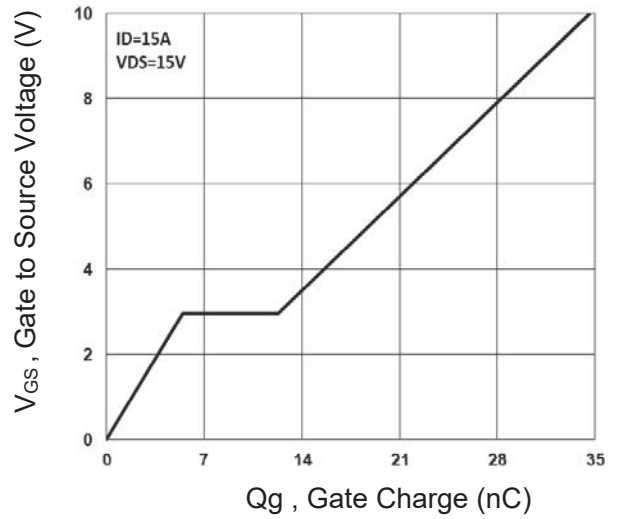
**Fig.1 Continuous Drain Current vs. TC**



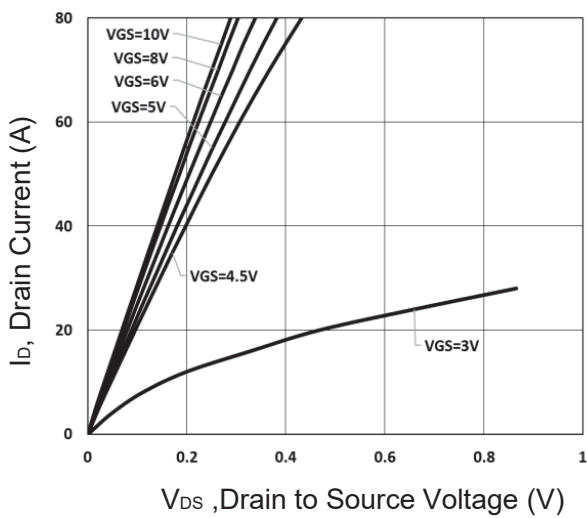
**Fig.2 Normalized RDSON vs. TJ**



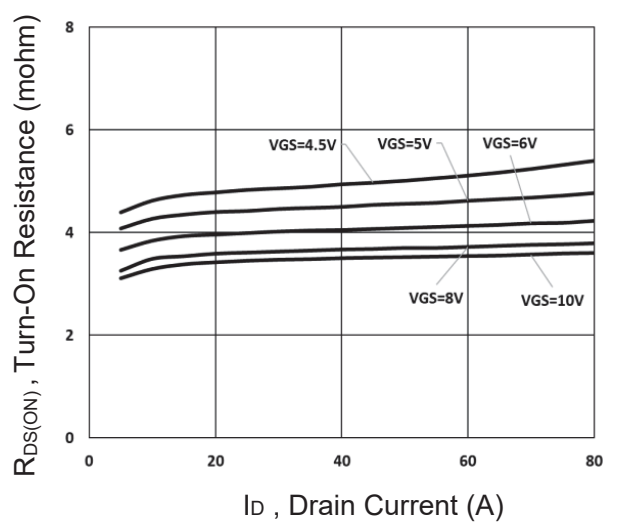
**Fig.3 Normalized Vth vs. TJ**



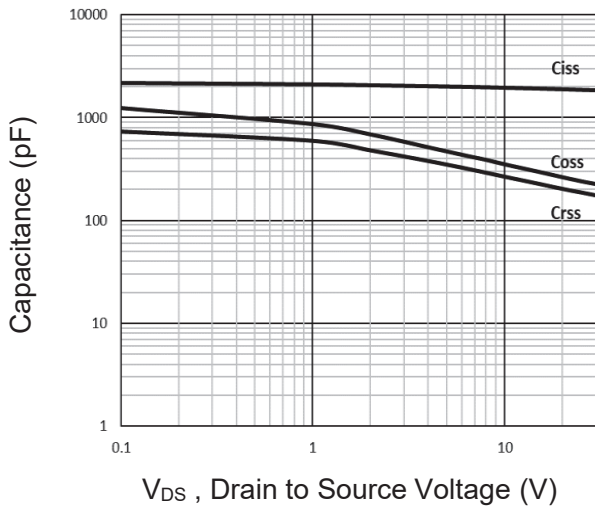
**Fig.4 Gate Charge Characteristics**



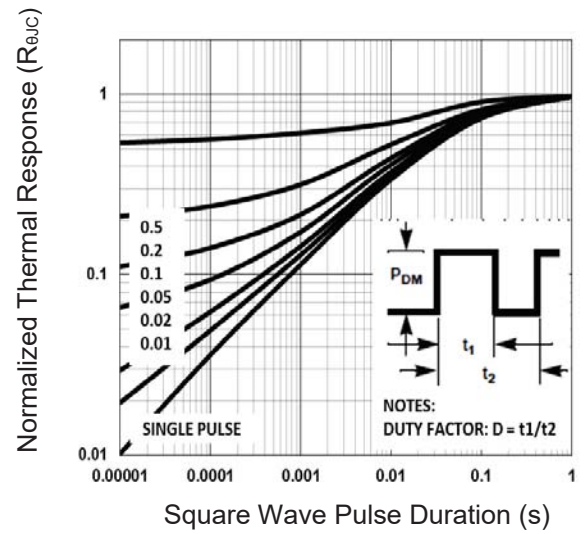
**Fig.5 Typical Output Characteristics**



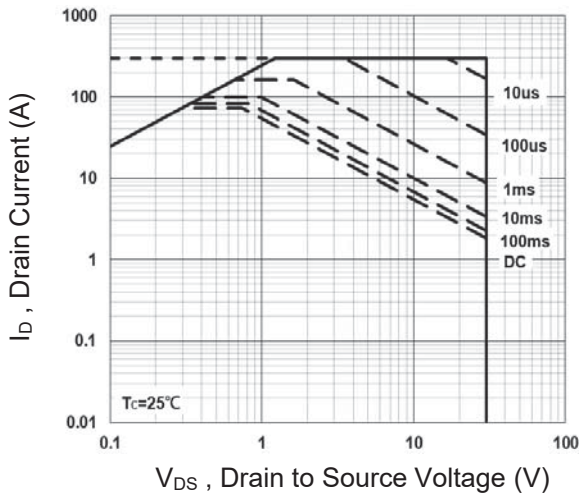
**Fig.6 Turn-On Resistance vs. ID**



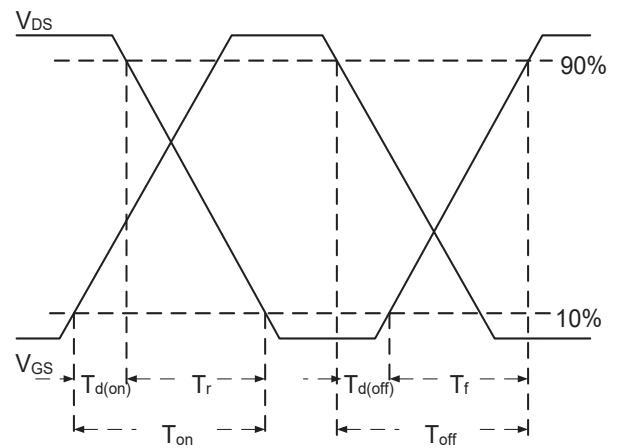
**Fig.7 Capacitance Characteristics**



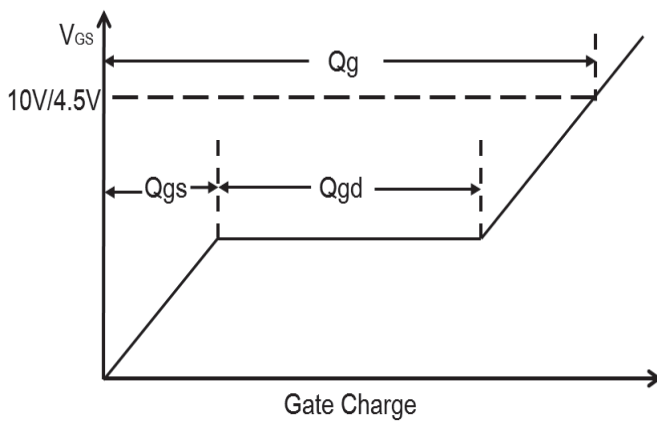
**Fig.8 Normalized Transient Impedance**



**Fig.9 Maximum Safe Operation Area**

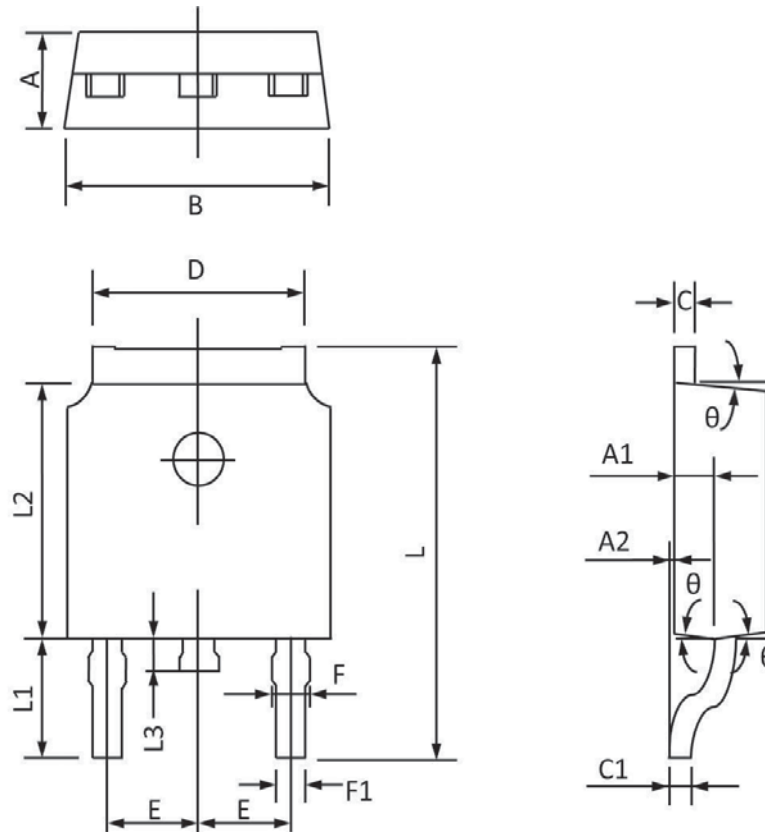


**Fig.10 Switching Time Waveform**



**Fig.11 Gate Charge Waveform**

## TO-252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.400	0.244	0.213
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°